

CX1HGSM AT CRYSTAL

8 MHz to 250 MHz

High Shock Miniature Surface Mount AT Quartz Crystal

Fundamental Mode: 8 MHz - 250 MHz Third Overtone Mode: 48 MHz - 160 MHz

DESCRIPTION

STATEK's miniature CX1HGSM AT crystals in leadless ceramic packages are designed for surface mounting on printed circuit boards or hybrid substrates. These rugged crystals are designed for applications requiring exceptional shock and vibration survival.

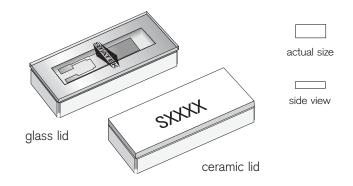
FEATURES

- High shock and vibration resistance
- Designed for surface mount applications using infrared, vapor phase, or epoxy mount techniques
- Low profile hermetically sealed ceramic package
- Available with glass or ceramic lid
- Custom designs available
- Full military testing available
- Designed and manufactured in the USA

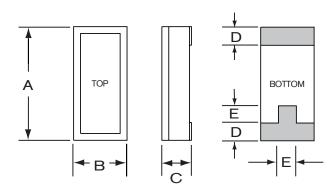
APPLICATIONS

Industrial

- Down-hole Data Recorder
- Process Control
- Environmental Control
- Engine Control
- Telemetry
- Ruggedized Instrumentation
- Automotive Control
- Military & Aerospace
 - Smart Munitions
 - Timing Devices (Fuzes)
 - Surveillance Devices
 - Missile Telemetry
 - Ruggedized Communications
- www.DataSheet411.com



PACKAGE DIMENSIONS



	TYPICAL		MAXIMUM		
DIM	inches	mm	inches	mm	
А	0.315	8.00	0.330	8.38	
В	0.140	3.56	0.155	3.94	
С	-	-	see below		
D	0.045	1.14	0.055	1.40	
E	0.060	1.52	0.070	1.78	

THICKNESS (DIM C) MAXIMUM

	GLASS LID		CERAMIC LID	
	inches	mm	inches	mm
SM1	0.065	1.65	0.070	1.78
SM2/SM4	0.067	1.70	0.072	1.83
SM3/SM5	0.070	1.78	0.075	1.90

10108 - Rev B

SGS

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SPECIFICATIONS

Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice.

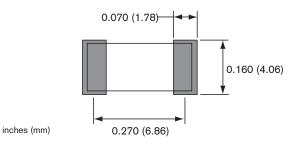
Fundamental Frequency	<u>10 MHz</u>	<u>32 MHz</u>	<u>155.52 MHz</u>	
Motional Resistance R_1 (Ω)	30	25	15	
Motional Capacitance C_1 (fF)	5.5	6.2	4.0	
Quality Factor Q (k)	100	30	30	
Shunt Capacitance C_0 (pF)	2.2	2.3	2.3	
Calibration Tolerance ¹	± 100 pp	m, or tighte	er as required	
Load Capacitance ²	20 pF for	$f \le 50 \text{ MH}$	lz	
	10 pF for	f > 50 MH	Ηz	
Drive Level	500 μW MAX for f \leq 50 MHz			
	200 µW I	MAX for f :	> 50 MHz	
Frequency-Temperature	± 50 ppm	to ± 10	ppm (Commercial)	
Stability ^{1,3}	\pm 100 ppm to \pm 20 ppm (Industrial)			
	± 100 ppr	m to ±30	opm (Military)	
Aging, first year ⁴	10 ppm N	AX		
Shock, survival⁵	10,000 g,	0.2 ms, 1	/2 sine	
Vibration, survival ⁶	50 g, 10-9	2,000 Hz s	swept sine	
Operating Temp. Range	-10°C to +	+70°C (C	ommercial)	
	-40°C to -	⊦85°C (In	dustrial)	
	-55°C to -	⊦125°C (M	lilitary)	
Storage Temp. Range	-55°C to +	⊦125°C.		
Max Process Temperature	260°C for 20 sec.			

TERMINATIONS

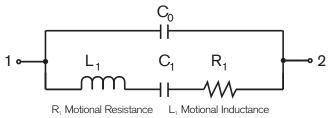
Designation	<u>Termination</u>
SM1	Gold Plated (Lead Free)
SM2	Solder Plated
SM3	Solder Dipped
SM4	Solder Plated (Lead Free)
SM5	Solder Dipped (Lead Free)

Max Process Temperature 260°C for 20 sec.

SUGGESTED LAND PATTERN



EQUIVALENT CIRCUIT



 C_1 Motional Capacitance C_0 Shunt Capacitance

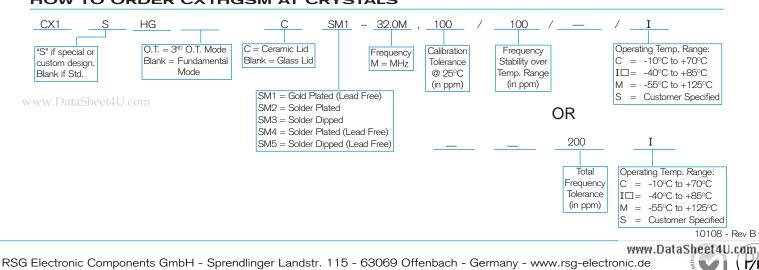
1. Other tolerances available. Contact factory.

- 2. Unless specified otherwise.
- 3. Does not include calibration tolerance. The characteristics of the frequency stability over temperature follow that of the AT thickness-shear mode.
- 4. 10 ppm MAX for frequencies below 40 MHz. For tighter tolerances and higher frequencies contact factory.
- 5. Up to 100,000 g. Contact factory.
- 6. Per MIL-STD-202G, Method 204D, Condition E. Random vibration testing also available.

PACKAGING OPTIONS

- Tray Pack
- 16mm tape, 7" or 13" reels Per EIA 481 (see Tape and Reel data sheet 10109)

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HOW TO ORDER CX1HGSM AT CRYSTALS